

Tflex™ HP34 Series Thermal Gap Filler



PRODUCT DESCRIPTION

Tflex HP34 is a new development product within Laird's high-performance material portfolio. The high performing gap filler consists of graphite fibers expertly aligned to provide a very high bulk thermal conductivity. In addition to the high bulk Tc, Tflex HP34 is uniquely designed to maintain its thermal performance within an application under increased pressure. Best performance will occur at lower pressures, 10-30 psi.

FEATURES AND BENEFITS

- 34 W/mK bulk thermal conductivity
- Silicone Free formulation
- Maintains thermal performance under increased pressure
- Low contact resistance with mating surfaces
- Environmentally friendly solution that meets RoHS and REACH

TYPICAL PROPERTIES

PROPERTIES	TYPICAL VALUE	TEST METHOD
Construction & Composition	Aligned Graphite	N/A
Color	Grey	Visual
Thickness Range	1mm - 5mm	N/A
Thickness Tolerance	+/- 10%	N/A
Bulk Thermal Conductivity	34 W/mk	ASTM D5470
Density	2.3 g/cc	Helium Pycnometer
Thermal Resistance (1.5mm) @ 30% deflection, 50 °C	0.589 °C*cm ² /W (0.096 °C*in ² /W)	ASTM D5470
Temperature Range	-40 ⁰ C to 125 ⁰ C	Laird Test Method
Hardness Shore 00 (3 second)	50	ASTM D2240
Hardness Shore 00 (30 second)	20	ASTM D2240
Volume Resistivity (Ω cm)	10 Ω-cm	ASTM D991
UL Flammability Rating	V-0 (Pending)	UL 94



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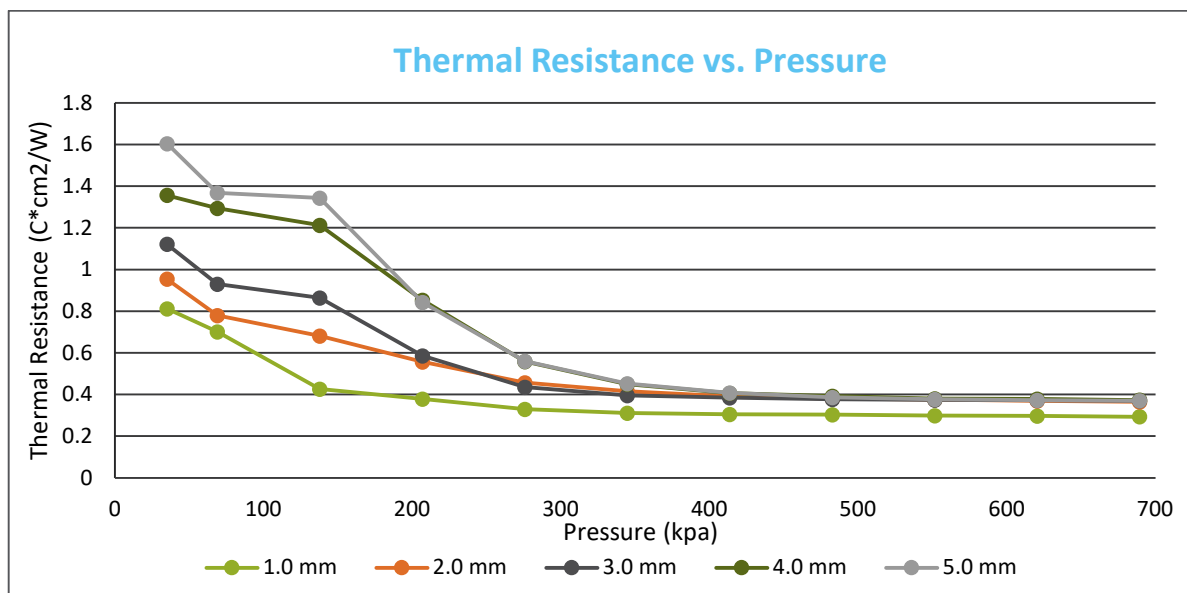
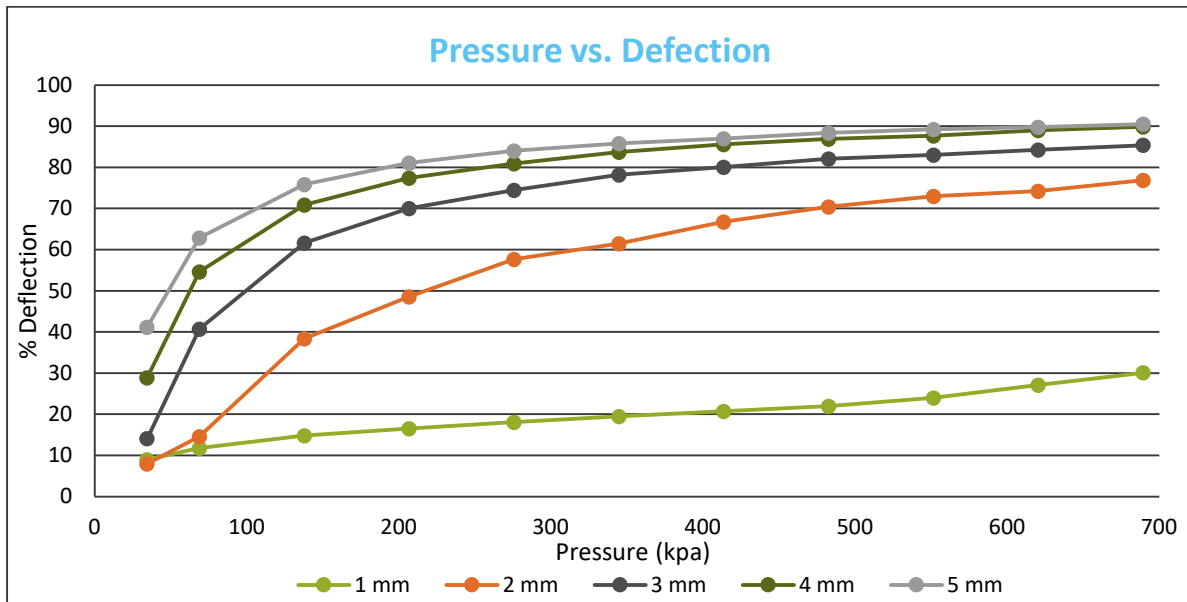
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A18332-00 Tflex HP34 Data Sheet 08182023

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AVAILABILITY

- 1 mm (0.040”) to 5.0 mm (0.200”) thick material available in 0.25mm (0.010”) increments
- Available in standard sheet sizes of 3”x 5” (76.2mm x 127mm) or custom die cut parts

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. Tflex HP34 is the material name, followed by the thickness. EX: Tflex™ HP34,1.00 = 1.00mm thick Tflex HP34 material

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